

N-Channel Enhancement Mode Field Effect Transistor

Product Summary

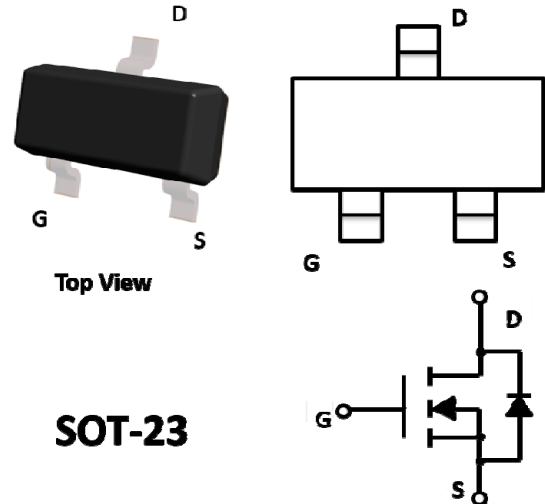
- V_{DS} 60V
- I_D 3.0A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) < 125 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 135 mohm

General Description

- Trench Power MV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

- DC-DC Converters
- Power management functions



Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^{\circ}C$	I_D	3	A
	$T_A=70^{\circ}C$		2.4	
Pulsed Drain Current ^A		I_{DM}	12	A
Total Power Dissipation @ $T_c=25^{\circ}C$		P_D	1.2	W
Thermal Resistance Junction-to-Ambient ^B		$R_{\theta JA}$	105	$^{\circ}C/W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^{\circ}C$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS1}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
	I _{GSS2}	V _{GS} = ±10V, V _{DS} =0V			±50	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.3	2.0	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D =3A		105	125	mΩ
		V _{GS} = 4.5V, I _D =2A		125	135	
Diode Forward Voltage	V _{SD}	I _S =3.0A, V _{GS} =0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I _S				3.0	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHz		330		pF
Output Capacitance	C _{oss}			90		
Reverse Transfer Capacitance	C _{rss}			17		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =3.0A		5.1		nC
Gate-Source Charge	Q _{gs}			1.3		
Gate-Drain Charge	Q _{gd}			1.7		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =30V, I _D =1.5A, R _L =1Ω R _{GEN} =3Ω		13		ns
Turn-on Rise Time	t _r			51		
Turn-off Delay Time	t _{D(off)}			19		
Turn-off fall Time	t _f			12		

A. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Performance Characteristics

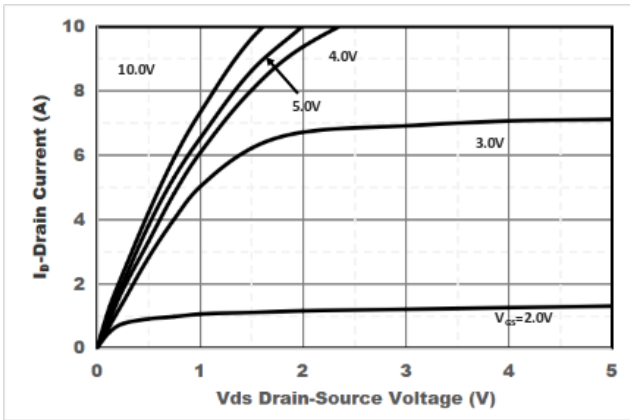


Figure1. Output Characteristics

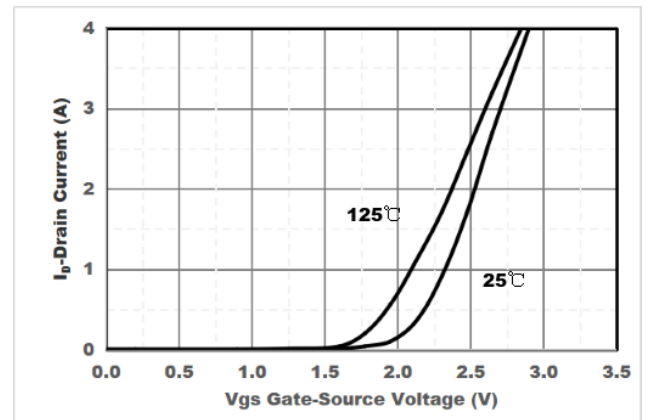


Figure2. Transfer Characteristics

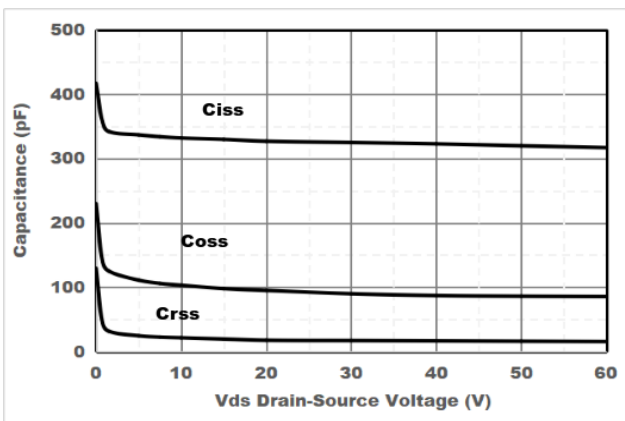


Figure3. Capacitance Characteristics

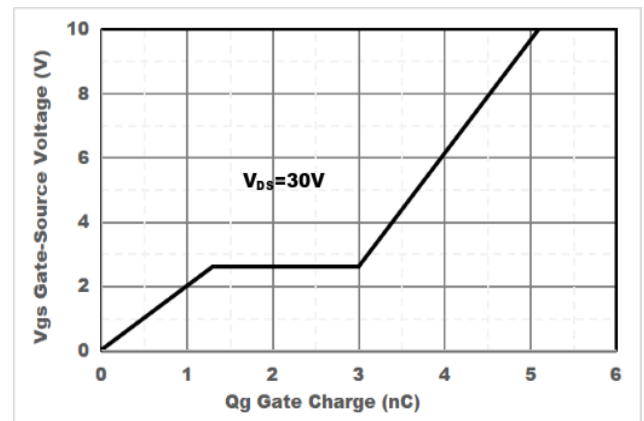


Figure4. Gate Charge

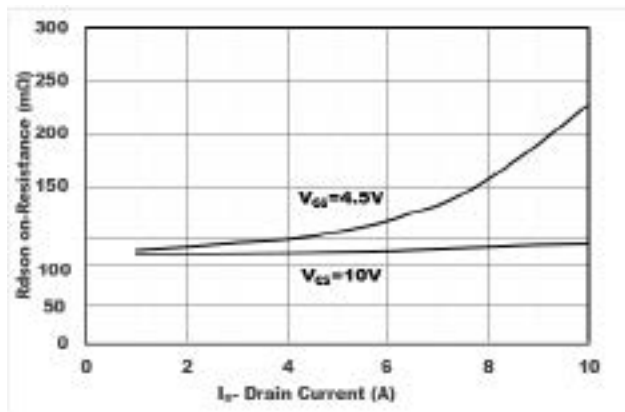


Figure5. Drain-Source on Resistance

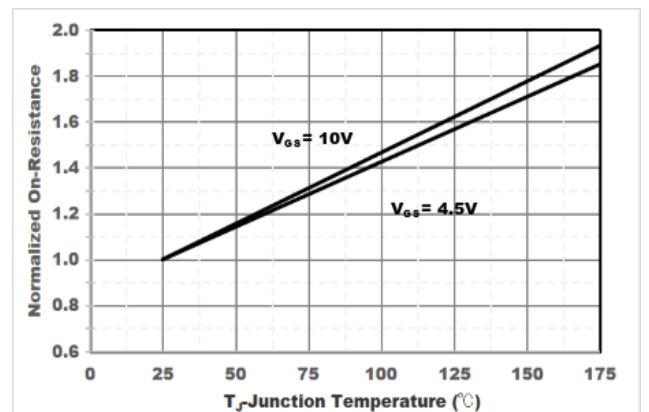


Figure6. Drain-Source on Resistance

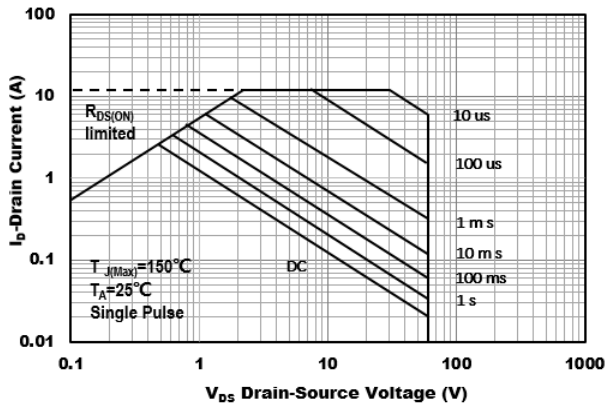


Figure7. Safe Operation Area

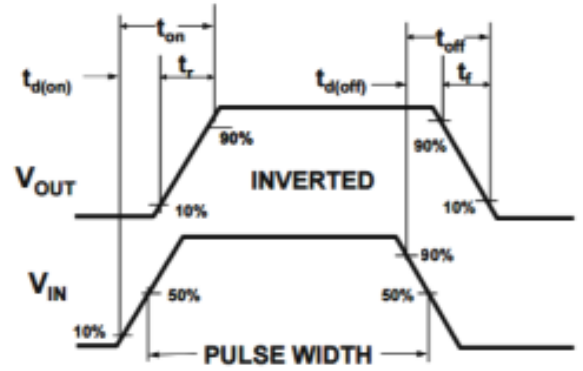
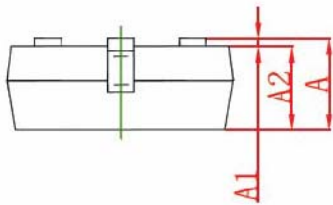
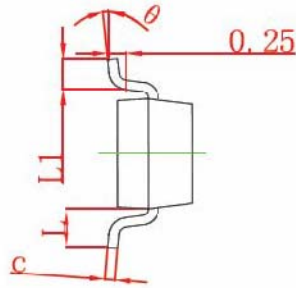
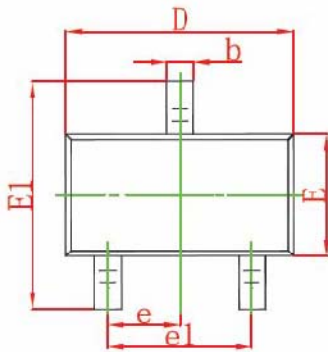


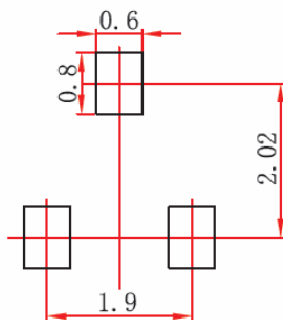
Figure8. Switching wave

SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
c	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.